

Opening - The 21st Interfinish World Congress & Seminar (25 Nov,2024) 2024 年 11 月 25 日 - 第 21 届世界表面精饰大会暨研讨会开幕日

Schedule 时间表 1st Day Diamond Hall

0830-0900	Registration 注册
0900-0930	Opening and Group Photo 开幕式及合照
0930-1000	Plenary Talk 1 by Ma Jie (CSEA) 会议演讲 1 – 马捷 (中国表面工程协会) Surface Engineering Technology 40 Years Of Progress In China 中国表面工程技术的 40 年发展
1000-1030	Plenary Talk 2 by Jimmy Kwok (HKSFS) 会议演讲 2 – 郭振华 (香港表面处理学会) A New Chapter For Materials Finishing In HK and Greater Bay Area
1030-1105	Break 休息, visiting program 导赏团 和 Booth visit 摊位参观
1105-1150	Plenary Talk 3 by Prof K. Ryder (IMF UK) 会议演讲 3 – Prof Ryder (英国 IMF) Sustainable Manufacturing In The Finishing Industries And The Management Of Critical Technology Metals
1150-1315	Lunch time 午餐
1315-1400	Plenary Talk 4 by Prof S. Moon (Korean Society of Surface Science and Engineering) 会议演讲 4 – Prof Moon (韩国表面工程学会) Surface Finishing Technologies for Light Metals
1400-1445	Plenary Talk 5 by Dr. T. Gotsick (MacDermid Enthone) 会议演讲 5 – Dr. Gotsick (麦德美乐思) How Surface Finishing Can Contribute to A Cleaner World
1445-1530	Plenary Talk 6 by Prof Lawrence Li (City University of HK)会议演讲 6 – 李国恩教授(城大) Multilayer DLC For High-Contact Stress Applications
1530-1600	Break 休息, visiting program 导赏团 和 Booth visit 摊位参观
1600-1645	Plenary Talk 7 by Prof Kanematsu (Suzuka College)/Prof Kure (Nagoya Institute of Technology) representing Surface Finishing Society of Japan 会议演讲 7 – 兼松秀行教授 (铃鹿工业高等专门学校)/吴松竹教授(名古屋工业大学)日本表面技术协会代表 Graphene & Graphene Oxide Dispersed Alkoxysilane Resin Coatings And Their Biofilm Properties
1645 - 1730	Plenary Talk 8 by Prof Sawada (Nagoya University Japan) 会议演讲 8 – 泽田康之教授(日本名古屋大学) Plasma Processing and Its Application to Materials for Energy Storage Devices
1730-1745	Closing Remarks 散会词
1900-2130	Conference Dinner and HKSFS 50 th Anniversary Dinner 晚宴

Day Two - The 21st Interfinish World Congress & Seminar (26 Nov, 2024)
2024 年 11 月 26 日 - 第 21 届世界表面精饰大会暨研讨会

Schedule 时间表 2nd Day Plantinum Hall(T1)

0845-0900	Registration 注册
Advanced Materials Finishing	
0900-0940	Prof LI Ning (Harbin Institute of Technology) 李宁教授(哈工大) Preparation and Action Mechanism of Iridium-Coated Titanium Anode for Copper Plating of PCB With Low Additive Breakdown
0940-1020	Prof. ZHENG Zijian/Dr. Huang Qiyao (Hong Kong Polytechnic University) 郑子剑教授(理大) Polymer-assisted Metal Deposition for Flexible Electronics
1020-1035	Break 休息
1035-1115	Prof. CHEN Yuanming (University of Electronic Science & Technology of China) 陈苑明教授(电子科技大学) Construction of Functional Metal Deposition Layer on Some Materials
1115-1155	Prof Shochiku Kure (Nagoya Institute of Technology) 吴松竹教授(名古屋工业大学) Tailored Fabrication of New Functional Composite Coatings on Various Non-Ferrous Metals Through Hybrid Surface Technologies for Next Generation Power Devices and High-Performance Batteries
1155-1315	Lunch time 午餐
1315-1355	Prof SUN Jian Jun (Fuzhou University) 孙建军教授(福州大学) Bump Electrodeposition Of Tin-Based Alloy Advanced Packaging
1355-1435	Prof. Tsunehisa Suzuki (Akita Prefectural University) 鈴木庸久教授(秋田県立大学) Nickel Deposition Mechanism Of Laser-Enhanced Electroless Plating Using CW Laser
Surface Finishing from Industrialization to Green Technology Development	
1435-1515	Prof. Lin An (Wuhan University 林安教授(武汉大学) Application Of Closed Cycle Technology In Electroplating Production Line In China
1515-1530	Break 休息
1530-1610	Prof. Sik Chol Kwon (Inha University – Graduate School of Engineer) Surface Technology, The Foundation of Korea's Industrial Development
1610-1650	Nicholas Chang (HKSFS) 张志恒(香港表面处理学会) Surface Finishing From Industrialization To Green Technology Development
1650-1730	Closing Remarks 散会词

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Schedule 时间表 2nd Day Gold Hall(T2)

0845-0900	Registration 注册
Electronics Plating and Electroless Plating	
0900-0940	Prof Cui Guofeng (Sun Yat-sen University) 崔国峰教授(中山大学) Electronic packaging gold Tin Electroplating and Development of Electroplating Testing Instrument Research 电子封装金锡电镀和电镀检测仪器开发
0940-1020	Dr. Jiang Jianping (Nantong Xingshengyi New Materials Technology Co., Ltd) 江建平(南通星盛亿新材料科技有限公司) Opportunities of ENIG/ENEPIG Technology in Advanced Electronics Manufacturing
1020-1035	Break 休息
1035-1115	Dr. Xiao Ning (Beijing University of Chemical Technology) 肖宁博士(北京化工大学) Synthesis And Performance Research Of Copper Plating Additives Used For PCB Microvia Filling
1115-1155	Prof FU Xian Zhu (Shenzhen University) 符显珠教授(深圳大学) Electroless Deposition Technology for Electrical Interconnections
1155-1315	Lunch time 午餐
Industrial Applications of Surface Finishing	
1315-1355	Prof. Yuttanant Boonyongmaneerat (Chulalongkorn University Thailand) Collaborative Research to Advance Nickel-Based Electrodeposition for High-Erosion and High-Temperature Applications
1355-1435	Prof. Jonathan Chung (City University of Hong Kong) 钟志源教授(香港城市大学) Good Practices In Mechanical Polishing Before More Precise Surface Finishing And Advanced Coating For Automotive And Watches Industries.
1435-1515	Mr. David Shi 史宏伟 (天津艾隆科技开发有限公司) The Development and Frontier of Aluminium Surface Treatment 铝表面处理的发展与前沿
1515-1530	Break 休息
1530-1610	Zhao Yongqiang 赵永强 – 深圳市顺信精细化工有限公司 /遂宁迪印科技有限公司 All-Solution-Processed Metallization of Through Glass Vias (TGVs) with a High Adhesion Promoting Layer (APL)
1610-1650	Feng Xiaolong 冯小龙 (宁波康强电子股份有限公司) Roll-to-Roll Continuous High-Precision Selective Photoresist Electroplating and Highly Reliable Brown Oxidation Technology
1650-1730	Closing Remarks 散会词 (Join in Platinum Hall)